

# DZ2J062

## Silicon epitaxial planar type

For constant voltage / waveform clipper and surge absorption circuit

Low noise type

### ■ Features

- Excellent rising characteristics of zener current  $I_Z$
- Eco-friendly Halogen-free package

### ■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	$I_{FRM}$	200	mA
Total power dissipation *	$P_T$	200	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*:  $P_T = 200$  mW achieved with a printed circuit board.

### ■ Package

- Code  
SMini2-F5-B
- Pin Name
  1. Cathode
  2. Anode

### ■ Marking Symbol: FJ, FU

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 10$ mA			1.0	V
Zener voltage *1, 2, 4	$V_Z$	$I_Z = 5$ mA	5.89		6.51	V
Zener operating resistance	$R_Z$	$I_Z = 5$ mA			30	$\Omega$
Zener rise operating resistance	$R_{ZK}$	$I_Z = 0.5$ mA			100	$\Omega$
Reverse current	$I_R$	$V_R = 4.0$ V			0.2	$\mu\text{A}$
Temperature coefficient of zener voltage *3	$S_Z$	$I_Z = 5$ mA		2.4		mV/ $^\circ\text{C}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 5 MHz.

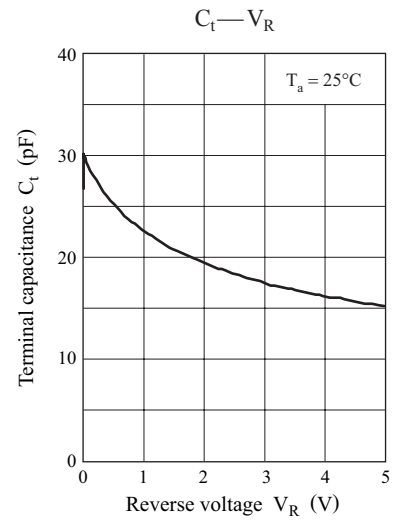
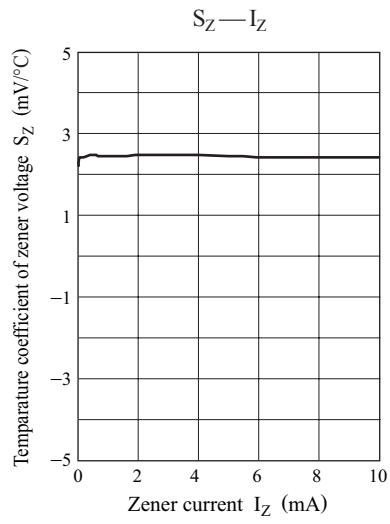
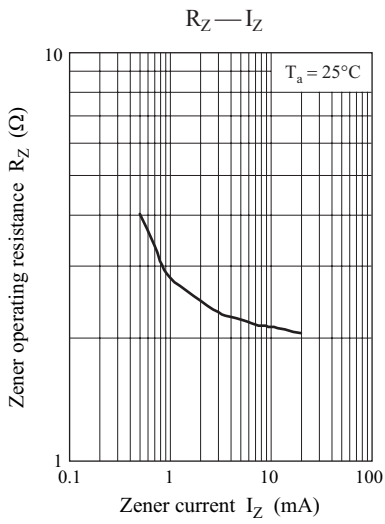
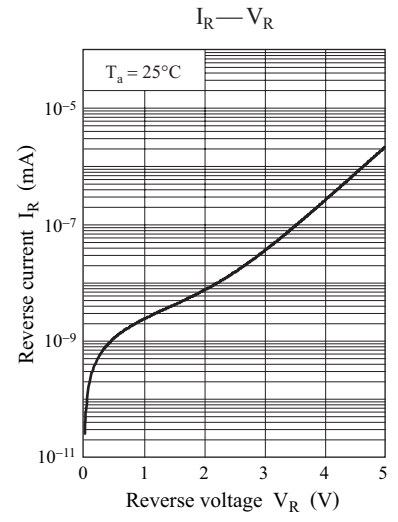
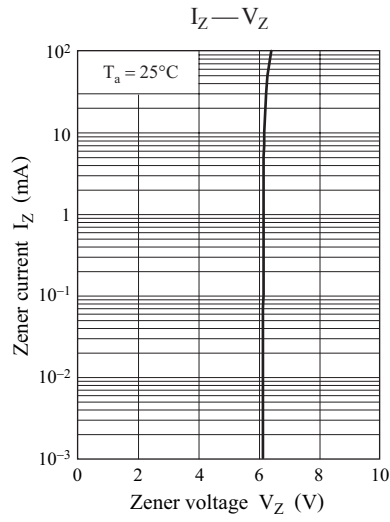
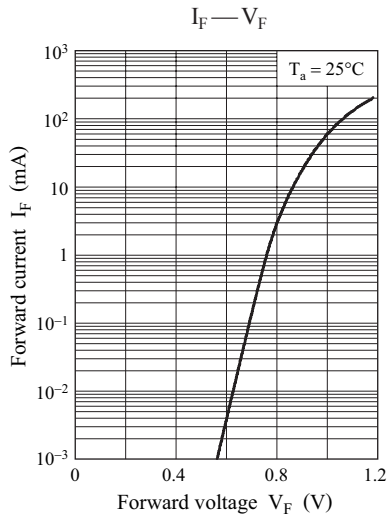
3. \*1: The temperature must be controlled  $25^\circ\text{C}$  for  $V_Z$  measurement.  $V_Z$  value measured at other temperature must be adjusted to  $V_Z(25^\circ\text{C})$

\*2:  $V_Z$  guaranteed 20 ms after current flow.

\*3:  $T_j = 25^\circ\text{C}$  to  $150^\circ\text{C}$

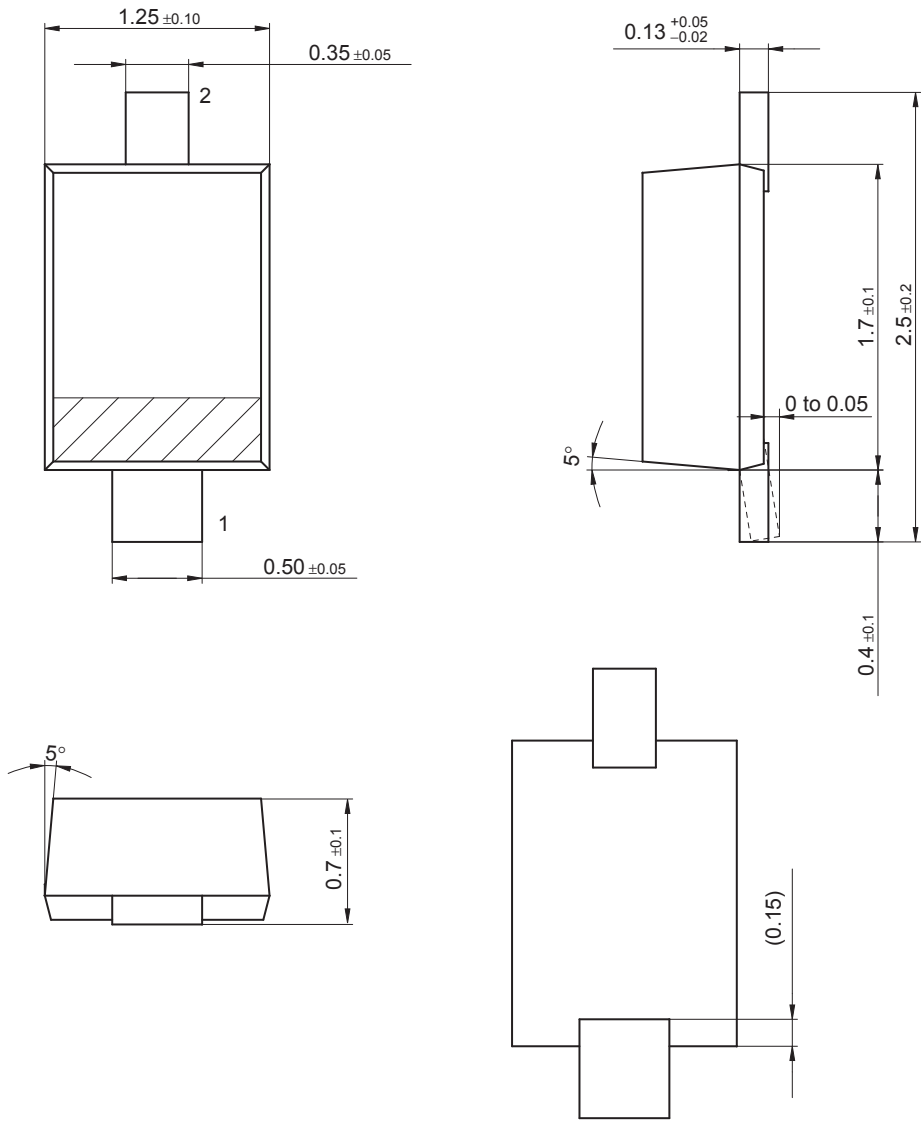
\*4: Rank classification

Code	M	0
Rank	M	No-rank
$V_Z$	6.05 to 6.36	5.89 to 6.51
Marking Symbol	FU	FJ



SMini2-F5-B

Unit: mm



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